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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

2010	
Product Status	Discontinued at Digi-Key
Core Processor	80515
Core Size	8-Bit
Speed	24MHz
Connectivity	I ² C, SmartCard, UART/USART, USB
Peripherals	LED, POR, WDT
Number of I/O	9
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VFQFN Exposed Pad
Supplier Device Package	44-QFN (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/analog-devices/73s1215f-44im-f-p

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

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Internal Data Memory: The Internal data memory provides 256 bytes (0x00 to 0xFF) of data memory. The internal data memory address is always one byte wide and can be accessed by either direct or indirect addressing. The Special Function Registers occupy the upper 128 bytes. This SFR area is available only by direct addressing. Indirect addressing accesses the upper 128 bytes of Internal RAM.

The lower 128 bytes contain working registers and bit-addressable memory. The lower 32 bytes form four banks of eight registers (R0-R7). Two bits on the program memory status word (PSW) select which bank is in use. The next 16 bytes form a block of bit-addressable memory space at bit addresses 0x00-0x7F. All of the bytes in the lower 128 bytes are accessible through direct or indirect addressing. Table 4 shows the internal data memory map.

Address	Direct Addressing	Indirect Addressing			
0xFF	Special Function	DAM			
0x80	Registers (SFRs)	RAM			
0x7F	Dute ed				
0x30	Byle-au	dressable area			
0x2F	Dute er hit addresseble eres				
0x20	Byte or bit-addressable area				
0x1F	Register banks R0…R7 (x4)				
0x00	Register ba	11K5 KUKI (X4)			

External Data Memory: While the 80515 can address up to 64KB of external data memory in the space from 0x0000 to 0xFFFF, only the memory ranges shown in Figure 2 contain physical memory. The 80515 writes into external data memory when the MPU executes a MOVX @Ri,A or MOVX @DPTR,A instruction. The MPU reads external data memory by executing a MOVX A,@Ri or MOVX A,@DPTR instruction.

There are two types of instructions, differing in whether they provide an eight-bit or sixteen-bit indirect address to the external data RAM.

In the first type (MOVX A,@Ri), the contents of R0 or R1, in the current register bank, provide the eight lower-ordered bits of address. This method allows the user access to the first 256 bytes of the 2KB of external data RAM. In the second type of MOVX instruction (MOVX A,@DPTR), the data pointer generates a sixteen-bit address.

Address	Use	Address	Use						
0xFFFF		0xFFFF	Peripheral Control Registers (128b) Smart Card Control						
		0XFF80							
		0xFF7F							
		0XFE00	(384b)						
		0xFDFF	LISP Degisters (512b)						
		0XFC00	USB Registers (512b)						
		0xFBFF							
		0x0800	-			U	se		
	Flash Program Memory 64K		Address	Indirect Access	Direct Access				
			0xFF		SFRs				
					0x80	Byte RAM	SERS		
					0x7F	- Byte RAM			
	Bytes				0x48				
							0x47	Dit/Duto DAM	
					0x20	Bit/Byte RAM			
		XRAM		0x1F	Desister bank 2				
					0x18	Register bank 3 Register bank 2			
					0x17				
					0x10				
						0x0F	- Register bank 1		
		0			0x08				
				0x07	Denista	r book 0			
0x0000			0x0000		0x00	Registe	r bank 0		
Program Memory External Data Memory					Int	ternal Data M	emory		

Figure 2: Memory Map

Dual Data Pointer: The Dual Data Pointer accelerates the block moves of data. The standard DPTR is a 16-bit register that is used to address external memory. In the 80515 core, the standard data pointer is called DPTR, the second data pointer is called DPTR1. The data pointer select bit chooses the active pointer. The data pointer select bit is located at the LSB of the DPS IRAM special function register (DPS.0). DPTR is selected when DPS.0 = 0 and DPTR1 is selected when DPS.0 = 1.

The user switches between pointers by toggling the LSB of the DPS register. All DPTR-related instructions use the currently selected DPTR for any activity.

Note: The second data pointer may not be supported by certain compilers.

The master clock control register enables different sections of the clock circuitry and specifies the value of the VCO Mcount divider. The MCLK must be configured to operate at 96MHz to ensure proper operation of some of the peripheral blocks according to the following formula:

MCLK = (Mcount * 2 + 4) * F_{XTAL} = 96MHz

Mcount is configured in the MCLKCtl register must be bound between a value of 1 to 7. The possible crystal or external clock frequencies for getting MCLK = 96MHz are shown in Table 12.

F _{XTAL} (MHz)	Mcount (N)
12.00	2
9.60	3
8.00	4
6.86	5
6.00	6

Table 12: Frequencies and Mcount Values for MCLK = 96MHz

Master Clock Control Register (MCLKCtl): 0x8F ← 0x0A

Table 13: The MCLKCtl Register

MSB							LSB	
HSOEN	KBEN	SCEN	USBEN	32KEN	MCT.2	MCT.1	MCT.0	

Bit	Symbol	Function
MCLKCtl.7	HSOEN	High-speed oscillator disable. When set = 1, disables the high-speed crystal oscillator and VCO/PLL system. Do not set this bit = 1.
MCLKCtl.6	KBEN	1 = Disable the keypad logic clock.
MCLKCtl.5	SCEN	1 = Disable the smart card logic clock.
MCLKCtl.4	USBEN	1 = Disable the USB logic clock.
MCLKCtl.3	32KEN	1 = Disable the 32Khz oscillator. When the 32kHz oscillator is enabled, the RTC and other circuits such as debounce clocks are clocked using the 32kHz oscillator output. When disabled, the main oscillator provides the 32kHz clock for the RTC and other circuits. Note: This bit must be set if there is no 32KHz crystal or the 44 pin package is used. Some internal clocks and circuits will not run if the oscillator is enabled and no crystal is connected.
MCLKCtl.2	MCT.2	This value determines the ratio of the VCO frequency (MCLK) to the high-
MCLKCtl.1	MCT.1	speed crystal oscillator frequency such that:
MCLKCtl.0	MCT.0	MCLK = (MCount*2 + 4)* F_{XTAL} . The default value is MCount = 2h such that MCLK = (2*2 + 4)*12.00MHz = 96MHz.

The MPU clock that drives the CPU core defaults to 3.6923MHz after reset. The MPU clock is scalable by configuring the MPU Clock Control register (MPUCKCtl).

Master Clock Control Register (MCLKCtl): 0x8F ← 0x0A

Table 18: The MCLKCtl Register

MSB							LSB	
HSOEN	KBEN	SCEN	USBEN	32KEN	MCT.2	MCT.1	MCT.0	

Bit	Symbol	Function
MCLKCtl.7	HSOEN*	High-speed oscillator enable. When set = 1, disables the high-speed crystal oscillator and VCO/PLL system. This bit is not changed when the PWRDN bit is set but the oscillator/VCO/PLL is disabled.
MCLKCtl.6	KBEN	1 = Disable the keypad logic clock. This bit is not changed in PWRDN mode but the function is disabled.
MCLKCtl.5	SCEN	1 = Disable the smart card logic clock. This bit is not changed in PWRDN mode but the function is disabled. Interrupt logic for card insertion/removal remains operable even with smart card clock disabled.
MCLKCtl.4	USBEN	1 = Disable the USB logic clock. This bit is not changed in PWRDN mode but the function is disabled.
MCLKCtl.3	32KEN	1 = Disable the 32Khz oscillator. This function is not affected by PWRDN mode. Note: This bit must be set if there is no 32KHz crystal or the 44 pin package is used. Some internal clocks and circuits will not run if the oscillator is enabled and no crystal is connected.
MCLKCtl.2	MCT.2	This value determines the ratio of the VCO frequency (MCLK) to the high-
MCLKCtl.1	MCT.1	speed crystal oscillator frequency such that:
MCLKCtl.0	MCT.0	MCLK = (MCount*2 + 4)*Fxtal. The default value is MCount = 2h such that MCLK = (2*2 + 4)*12.00MHz = 96MHz.

*Note: The HSOEN bit should never be set under normal circumstances. Power down control should only be initiated via use of the PWRDN bit in MISCtIO.

Miscellaneous Control Register 0 (MISCtI0): 0xFFF1 ← 0x00

Transmit and receive (TX and RX) pin selection and loop back test configuration are set up via this register.

	Table 38: The MISCIU Register							
MSB							LSB	
PWF	PWRDN – – – – – SLPBK SSEL						SSEL	
Bit	Symbol				Functio	on		
MISCtI0.7	PWRDN	This bit plac	es the	73S1215	F into a p	ower dow	n state.	
MISCtI0.6	_							
MISCtI0.5	_							
MISCtI0.4	-							
MISCtI0.3	-							
MISCtI0.2	-							
MISCtI0.1	SLPBK	1 = UART loop back testing mode. The pins TXD and RXD are to be connected together externally (with SLPBK =1) and therefore: SLPBK SSEL Mode 0 0 normal using Serial_0 0 1 normal using Serial_1 1 0 Serial_0 TX feeds Serial_1 RX 1 1 Serial_1 TX feeds Serial_0 RX						
MISCtI0.0	SSEL	Selects either Serial_1 if set =1 or Serial_0 if set = 0 to be connected to RXD and TXD pins.						

Table 38: The MISCtI0 Register

1.7.4.1 Serial Interface 0

The Serial Interface 0 can operate in four modes:

• Mode 0

Pin RX serves as input and output. TX outputs the shift clock. 8 bits are transmitted with LSB first. The baud rate is fixed at 1/12 of the crystal frequency. Reception is initialized in Mode 0 by setting the flags in SOCON as follows: RI0 = 0 and REN0 = 1. In other modes, a start bit when REN0 = 1 starts receiving serial data.

• Mode 1

Pin RX serves as input, and TX serves as serial output. No external shift clock is used, 10 bits are transmitted: a start bit (always 0), 8 data bits (LSB first), and a stop bit (always 1). On receive, a start bit synchronizes the transmission, 8 data bits are available by reading SOBUF, and stop bit sets the flag RB80 in the Special Function Register SOCON. In mode 1 either internal baud rate generator or timer 1 can be use to specify baud rate.

Mode 2

This mode is similar to Mode 1, with two differences. The baud rate is fixed at 1/32 or 1/64 of oscillator frequency and 11 bits are transmitted or received: a start bit (0), 8 data bits (LSB first), a programmable 9th bit, and a stop bit (1). The 9th bit can be used to control the parity of the serial interface: at transmission, bit TB80 in SOCON is output as the 9th bit, and at receive, the 9th bit affects RB80 in Special Function Register SOCON.

• Mode 3

The only difference between Mode 2 and Mode 3 is that in Mode 3 either internal baud rate generator or timer 1 can be use to specify baud rate.

The SOBUF register is used to read/write data to/from the serial 0 interface.

M1	MO	Mode	Function				
0	0	Mode 0	Mode 0 13-bit Counter/Timer.				
0	1	Mode 1	Mode 1 16-bit Counter/Timer.				
1	0	Mode 2	Mode 2 8-bit auto-reload Counter/Timer.				
1	1	Mode 3	If Timer 1 M1 and M0 bits are set to '1', Timer 1 stops. If Timer 0 M1 and M0 bits are set to '1', Timer 0 acts as two independent 8-bit Timer/Counters.				

Table 42: Timers/Counters Mode Description

Mode 0

Putting either timer/counter into mode 0 configures it as an 8-bit timer/counter with a divide-by-32 prescaler. In this mode, the timer register is configured as a 13-bit register. As the count rolls over from all 1's to all 0's, it sets the timer overflow flag TF0. The overflow flag TF0 then can be used to request an interrupt. The counted input is enabled to the timer when TRx = 1 and either GATE = 0 or TX = 1 (setting GATE = 1 allows the timer to be controlled by external input TX, to facilitate pulse width measurements). TRx are control bits in the special function register TCON; GATE is in TMOD. The 13-bit register consists of all 8 bits of TH1 and the lower 5 bits of TL0. The upper 3 bits of TL0 are indeterminate and should be ignored. Setting the run flag (TRx) does not clear the registers. Mode 0 operation is the same for timer 0 as for timer 1.

Mode 1

Mode 1 is the same as mode 0, except that the timer register is run with all 16 bits.

Mode 2

Mode 2 configures the timer register as an 8-bit counter (TLx) with automatic reload. The overflow from TLx not only sets TFx, but also reloads TLx with the contents of THx, which is preset by software. The reload leaves THx unchanged.

Mode 3

Mode 3 has different effects on timer 0 and timer 1. Timer 1 in mode 3 simply holds its count. The effect is the same as setting TR1 = 0. Timer 0 in mode 3 establishes TL0 and TH0 as two separate counters. TL0 uses the timer 0 control bits: C/T, GATE, TR0, INT0, and TF0. TH0 is locked into a timer function (counting machine cycles) and takes over the use of TR1 and TF1 from timer 1. Thus, TH0 now controls the "timer 1" interrupt. Mode 3 is provided for applications requiring an extra 8-bit timer or counter. When timer 0 is in mode 3, timer 1 can be turned on and off by switching it out of and into its own mode 3, or can still be used by the serial channel as a baud rate generator, or in fact, in any application not requiring an interrupt from timer 1 itself.

1.7.9 Analog Voltage Comparator

The 73S1215F includes a programmable comparator that is connected to the ANA_IN pin. The comparator can be configured to trigger an interrupt if the input voltage rises above or falls below a selectable threshold voltage. The comparator control register should not be modified when the analog interrupt (ANAIEN bit in the INT6Ctl register) is enabled to guard against any false interrupt that might be generated when modifying the threshold. The comparator has a built-in hysteresis to prevent the comparator from repeatedly responding to low-amplitude noise. This hysteresis is approximately 20mV. The maximum voltage on the ANA_IN pad should be less than 3 volts. An external resistor divider is required for detecting voltages greater than 3.0 volts. Interrupt control is handled in the INT6Ctl register.

Analog Compare Control Register (ACOMP): 0xFFD0 ← 0x00

MSB							LSB	
ANALVL	_	ONCHG	CPOL	CMPEN	0	TSEL.1	TSEL.0	

Bit	Symbol	Function
ACOMP.7	ANALVL	When read, indicates whether the input level is above or below the threshold. This is a real time value and is not latched, so it may change from the time of the interrupt trigger until read.
ACOMP.6	-	
ACOMP.5	ONCHG	If set, the Ana_interrupt is invoked on any change above or below the threshold, bit 4 is ignored.
ACOMP.4	CPOL	If set = 1, Ana_interrupt is invoked when signal rises above selected threshold. If set = 0, Ana_interrupt is invoked when signal goes below selected threshold (default).
ACOMP.3	CMPEN	Enables power to the analog comparator. 1= Enabled. 0 = Disabled (default).
ACOMP.2	0	This value must be fixed at 0.
ACOMP.1	TSEL.1	Sets the voltage threshold for comparison to the voltage on pin ANA_IN. Thresholds are as follows: 00 = 1.00V
ACOMP.0	TSEL.0	01 = 1.24V 10 = 1.40V 11 = 1.50V

Table 60: The ACOMP Register

I2C Secondary Read Data Register (SRDR): 0XFF84 ← 0x00

Table 67: The SRDR Register

MSB							LSB	
SRDR.7	SRDR.6	SRDR.5	SRDR.4	SRDR.3	SRDR.2	SRDR.1	SRDR.0	

Bit	Function
SRDR.7	
SRDR.6	
SRDR.5	
SRDR.4	Second Data byte to be read from the I ² C slave device if bit 0 (I2CLEN) of the Control
SRDR.3	and Status register (CSR) is set = 1.
SRDR.2	
SRDR.1	
SRDR.0	

I2C Control and Status Register (CSR): 0xFF85 ← 0x00

Table 68: The CSR Register

MSB							LSB
_	_	—	_	-	AKERR	I2CST	I2CLEN

Bit	Symbol	Function
CSR.7	-	
CSR.6	-	
CSR.5	-	
CSR.4	-	
CSR.3	-	
CSR.2	AKERR	Set to 1 if acknowledge bit from Slave Device is not 0. Automatically reset when the new bus transaction is started.
CSR.1	I2CST	Write a 1 to start I ² C transaction. Automatically reset to 0 when the bus transaction is done. This bit should be treated as a "busy" indicator on reading. If it is high, the serial read/write operations are not completed and no new address or data should be written.
CSR.0	I2CLEN	Set to 1 for 2-byte read or write operations. Set to 0 for 1-byte operations.

LSB

Keypad Scan Time Register (KSCAN): 0xD3 ← 0x00

This register contains the values of scanning time and debouncing time.

Table 72: The KSCAN Register

MSB

DBTIME.5 DBTIME.4 DBTIME.3 DBTIME.2 DBTIME.1 DBTIME.0 SCTIME.1 SCTIME.0

Bit	Symbol	Function					
KSCAN.7	DBTIME.5						
KSCAN.6	DBTIME.4	De-bounce time in 4ms increments. $1 = 4ms$ de-bounce time, $0x3F = 252ms$, $0x00 = 256ms$. Key process and key releases are de bounced by					
KSCAN.5	DBTIME.3						
KSCAN.4	DBTIME.2	252ms, 0x00 = 256ms. Key presses and key releases are de-bounced this amount of time.					
KSCAN.3	DBTIME.1						
KSCAN.2	DBTIME.0						
KSCAN.1	SCTIME.1	Scan time in ms. 01 = 1ms, 02 = 2ms, 00 = 3ms, 00 = 4ms. Time between					
KSCAN.0	SCTIME.0	checking each key during keypad scanning.					

Keypad Control/Status Register (KSTAT): 0xD4 ← 0x00

This register is used to control the hardware keypad scanning and detection capabilities, as well as the keypad interrupt control and status.

Table 73: The KSTAT Register

MSB							LSB
-	-	_	_	KEYCLK	HWSCEN	KEYDET	KYDTEN

Bit	Symbol	Function
KSTAT.7	_	
KSTAT.6	-	
KSTAT.5	-	
KSTAT.4	-	
KSTAT.3	KEYCLK	The current state of the keyboard clock can be read from this bit.
KSTAT.2	HWSCEN	Hardware Scan Enable – When set, the hardware will perform automatic key scanning. When cleared, the firmware must perform the key scanning manually (bypass mode).
KSTAT.1	KEYDET	Key Detect – When HWSCEN = 1 this bit is set causing an interrupt that indicates a valid key press was detected and the key location can be read from the Keypad Column and Row registers. When HWSCEN = 0, this bit is an interrupt which indicates a falling edge on any Row input if all Row inputs had been high previously (note: multiple Key Detect interrupts may occur in this case due to the keypad switch bouncing). In all cases, this bit is cleared when read. When HWSCEN = 0 and the keypad interface 1kHz clock is disabled, a key press will still set this bit and cause an interrupt.
KSTAT.0	KYDTEN	Key Detect Enable – When set, the KEYDET bit can cause an interrupt and when cleared the KEYDET cannot cause an interrupt. KEYDET can still get set even if the interrupt is not enabled.

Smart card RST, I/O and CLK, C4, C8 shall be low before the end of the deactivation sequence. Figure 18 shows the timing for a deactivation sequence.

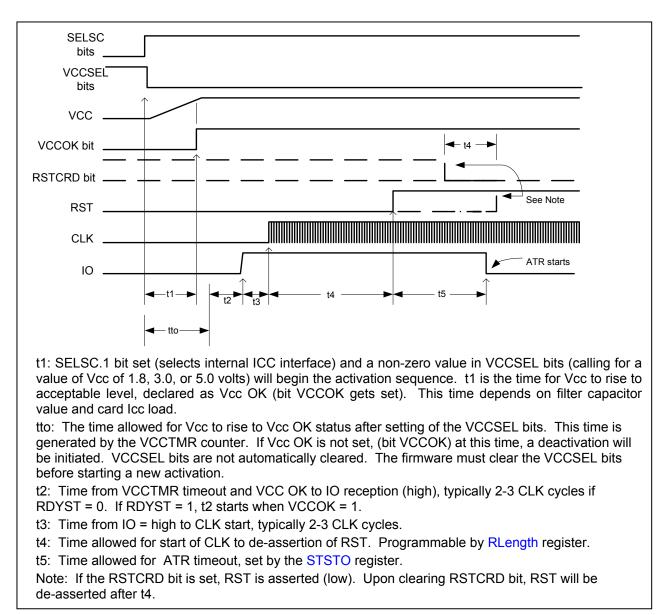


Figure 17: Asynchronous Activation Sequence Timing

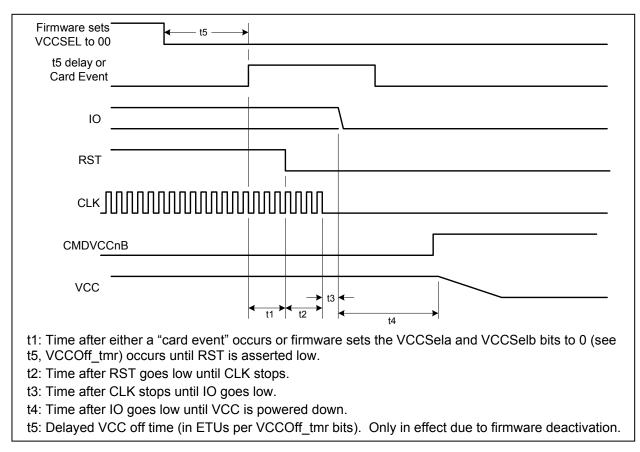


Figure 18: Deactivation Sequence

1.7.15.3 Data Reception/Transmission

When a 12Mhz crystal is used, the smart card UART will generate a 3.69Mhz (default) clock to both smart card interfaces. This will allow approximately 9600bps (1/ETU) communication during ATR (ISO 7816 default). As part of the PPS negotiation between the smart card and the reader, the firmware may determine that the smart card parameters F & D may be changed. After this negotiation, the firmware may change the ETU by writing to the SFR FDReg to adjust the ETU and CLK. The firmware may also change the smart card clock frequency by writing to the SFR SCCLK (SCECLK for external interface). Independent clock frequency control is provided to each smart card interface. Clock stop high or Clock stop low is supported in asynchronous mode. Figure 19 shows the ETU and CLK control circuits. The firmware determines when clock stop is supported by the smart card and when it is appropriate to go into that mode (and when to come out of it). The smart card UART is clocked by the same clock that is provided to the selected smart card. The transition between smart card clocks is handled in hardware to eliminate any glitches for the UART during switchover. The external smart card clock is not affected when switching the UART to communicate with the internal smart card.

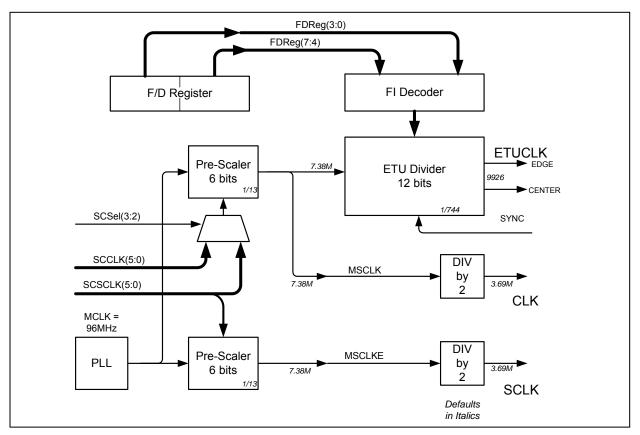


Figure 19: Smart Card CLK and ETU Generation

There are two, two-byte FIFOs that are used to buffer transmit and receive data. During a T=0 processing, if a parity error is detected by the 73S1215F during message reception, an error signal (BREAK) will be generated to the smart card. The byte received will be discarded and the firmware notified of the error. Break generation and receive byte dropping can be disabled under firmware control. During the transmission of a byte, if an error signal (BREAK) is detected, the last byte is retransmitted again and the firmware notified. Retransmission can be disabled by firmware. When a correct byte is received, an interrupt is generated to the firmware, which then reads the byte from the receive FIFO. Receive overruns are detected by the hardware and reported via an interrupt. During transmission of a message, the firmware will write bytes into the transmit FIFO. The hardware will send them to the smart card. When the last byte of a message has been written, the firmware will need to set the LASTTX bit in the STXCtI SFR. This will cause the hardware to insert the CRC/LRC if in a T=1 protocol mode. CRC/LRC generation/checking is only provided during T=1 processing. Firmware will need to instruct the smart function to go into receive mode after this last transmit data byte if it expects a response from the smart card. At the end of the smart card response, the firmware will put the interface back into transmit mode if appropriate.

The hardware can check for the following card-related timeouts:

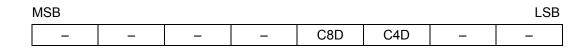
- Character Waiting Time (CWT)
- Block Waiting Time (BWT)
- Initial Waiting Time (IWT)

The firmware will load the Wait Time registers with the appropriate value for the operating mode at the appropriate time. Figure 20 shows the guard, block, wait and ATR time definitions. If a timeout occurs, an interrupt will be generated and the firmware can take appropriate recovery steps. Support is provided for adding additional guard times between characters (Extra Guard Time register) and between the last byte received by the 73S1215F and the first byte transmitted by the 73S1215F Block Guard Time register (BGT). Other than the protocol checks described above, the firmware is responsible for all protocol checking and error recovery.

C4/C8 Data Direction Register (SCDIR): 0xFE0C ← 0x00

This register determines the direction of the internal interface C4/C8 lines. After reset, all signals are tri-stated.

Table 92: The SCDIR Register



Bit	Symbol	Function
SCDIR.7	_	
SCDIR.6	-	
SCDIR.5	-	
SCDIR.4	-	
SCDIR.3	C8D	1 = input, 0 = output. Smart Card C8 direction.
SCDIR.2	C4D	1 = input, 0 = output. Smart Card C4 direction.
SCDIR.1	-	
SCDIR.0	-	

ISB

1.7.16 VDD Fault Detect Function

The 73S1215F contains a circuit to detect a low-voltage condition on the supply voltage V_{DD} . If enabled, it will deactivate the active internal smart card interface when V_{DD} falls below the V_{DD} Fault threshold. The register configures the V_{DD} Fault threshold for the nominal default of 2.3V* or a user selectable threshold. The user's code may load a different value using the FOVRVDDF bit =1 after the power-up cycle has completed

VDDFault Control Register (VDDFCtl): 0xFFD4 ← 0x00

Table 118: The VDDFCtl Register

MSB

INISD							LOD
_	FOVRVDDF	VDDFLTEN	_	STXDAT.3	VDDFTH.2	VDDFTH.1	VDDFTH.0

Bit	Symbol	Function				
VDDFCtl.7	-					
VDDFCtl.6	FOVRVDDF	Setting this bit high will allow the VDDFLT(2:0) bits set in this register to control the VDDFault threshold. When this bit is set low, the VDDFault threshold will be set to the factory default setting of 2.3V*.				
VDDFCtl.5	VDDFLTEN	Set = 1 will disable VDD Fault operation.				
VDDFCtl.4	-					
VDDFCtl.3	_					
VDDFCtl.2	VDDFTH.2	VDD Fault Threshold. Bit value(2:0) VDDFault voltage				
VDDFCtl.1	VDDFTH.1	000 2.3 (nominal default) 001 2.4 010 2.5				
VDDFCtl.0	VDDFTH.0	011 2.6 100 2.7 101 2.8 110 2.9 111 3.0				

* Note: The V_{DD} Fault factory default can be set to any threshold as defined by bits VDDFTH(2:0). The 73S1215F has the capability to burn fuses at the factory to set the factory default to any of these voltages. Contact Teridian for further details.

3.7.1 DC Characteristics

Symbol	Parameter	Condition	Min	Тур.	Max	Unit
I _{DD}	Supply Current	CPU clock @ 24MHz		30	35	mA
		CPU clock @ 12MHz		22	25.5	mA
		CPU clock @ 6MHz		16	19.5	mA
		CPU clock @ 3.69MHz		14	17	mA
		Power down (-40 to 85 C)		8	50	μA
		Power down (25 C)		6	13	μA
I _{PC}	Supply Current	V _{cc} on, ICC=0 I/O, AUX1, AUX2=high, CLK not toggling		450	650	μΑ
		Power down		1	10	
I _{PCOFF}	V_{PC} supply current when V_{CC} = 0	Smart card deactivated		345		μA

3.8 Voltage / Temperature Fault Detection Circuits

Symbol	Parameter	Condition	Min	Тур.	Max	Unit
V_{PCF}	V_{PC} fault (V_{PC} Voltage supervisor threshold)	V _{PC} <v<sub>CC, a transient event</v<sub>		V _{CC} > V _{PC} + 0.3		v
V _{CCF}	VCCOK = 0 (V _{CC} Voltage supervisor threshold)	$V_{\rm CC}$ = 5V			4.6	V
		V _{CC} = 3V			2.7	V
		V _{CC} = 1.8V			1.65	
T _F	Die over temperature fault		115		145	°C
ICCF	Vcc over current fault		110			mA

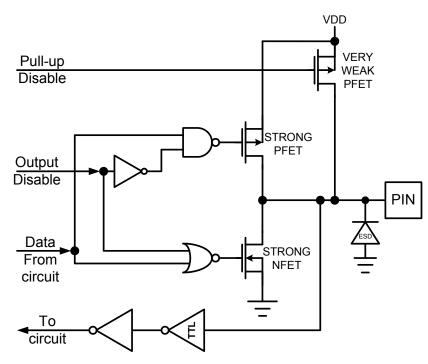
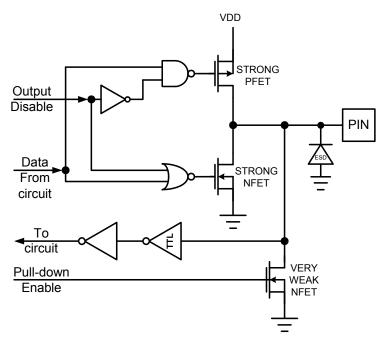


Figure 31: Digital I/O with Pull Up Circuit





5 Package Pin Designation

5.1 68-pin QFN Pinout

CAUTION: Use handling procedures necessary for a static sensitive component.

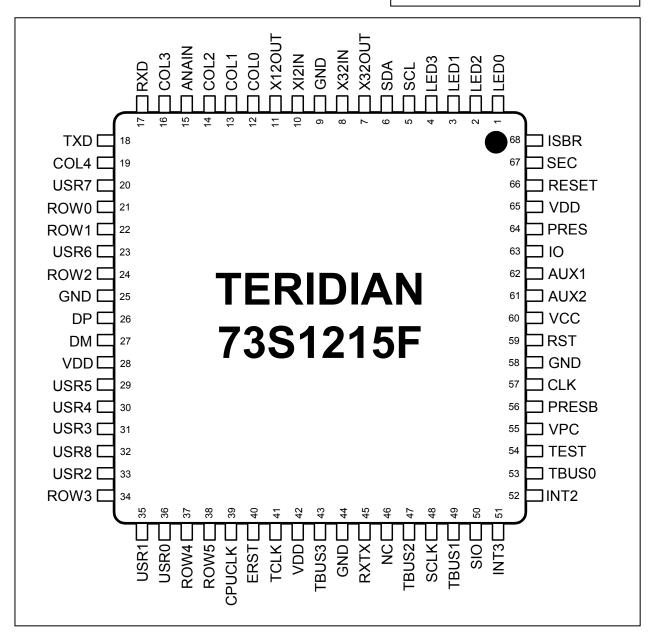


Figure 44: 73S1215F 68 QFN Pinout

6 Packaging Information

6.1 68-Pin QFN Package Outline

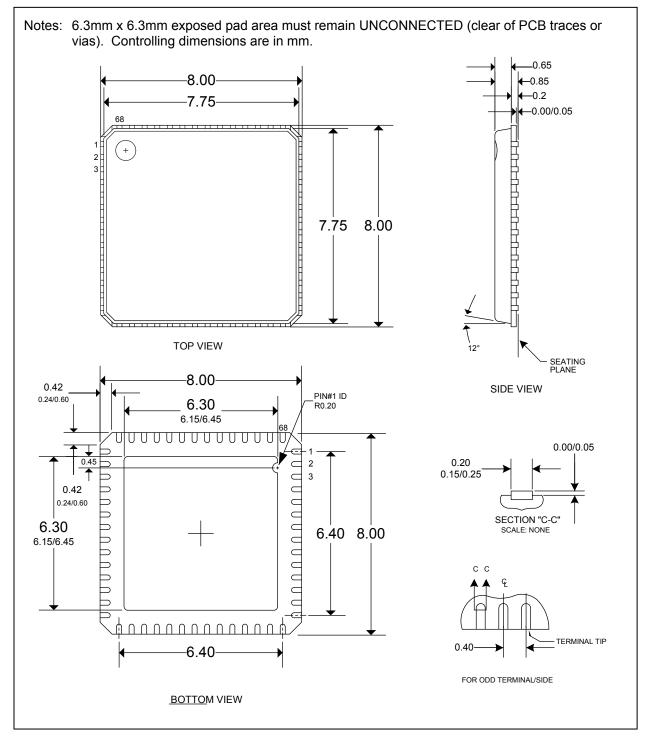


Figure 46: 73S1215F 68 QFN Package Drawing

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Teridian Semiconductor Corp., 6440 Oak Canyon, Suite 100, Irvine, CA 92618 TEL (714) 508-8800, FAX (714) 508-8877, http://www.teridian.com